

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC020N03LS G	**Issued**	11. November 2019
MA#	MA001630412		
Package	PG-TDSON-8-39	**Weight***	113.37 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.944	2.60	2.60	25968	25968
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.048	0.04		427	
	non noble metal	copper	7440-50-8	48.352	42.67	42.72	426509	427064
wire	non noble metal	copper	7440-50-8	0.039	0.03	0.03	343	343
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		711	
	plastics	epoxy resin	-	6.364	5.61		56134	
	inorganic material	silicondioxide	60676-86-0	33.833	29.84	35.52	298433	355278
leadfinish	non noble metal	tin	7440-31-5	1.520	1.34	1.34	13408	13408
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1398	1398
solder	non noble metal	tin	7440-31-5	0.053	0.05		465	
	noble metal	silver	7440-22-4	0.066	0.06		581	
	non noble metal	lead	7439-92-1	2.516	2.22	2.33	22191	23237
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	noble metal	silver	7440-22-4	0.150	0.13		1323	
	non noble metal	copper	7440-50-8	16.910	14.92	15.06	149162	150679
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2621	2625
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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